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MCOT128128BV-YM	128	x 128 OLED Module					
		Spe	cification				
Version: 1		-	Date: 03/10/2014				
	Revision						
1	30/09/2014	First	Issue				

Display F	eatures		
Resolution	128 x 128		
Appearance Yellow on Black			
Logic Voltage	2.8V		COHS
Interface	Multi	CO	ompliant
Module Size	33.80 x 43.70 x 1.41mm		
Operating Temperature	-40°C ~ +70°C	Box Quantity	Weight / Display
Construction	СОТ		

* - For full design functionality, please use this specification in conjunction with the SSD1327 specification. (Provided Separately)

Displ	ay Accessories	. —
Part Number	Description	AC

Optional Variants						
Appearance	Voltage					

SCOPE

The purpose of this specification is to define the general provisions and quality requirements that apply to the supply of display cells manufactured by T aaæ. This document, together with the Module Assembly Drawing, is the highest-level specification for this product. It describes the product, identifies supporting documents and contains specifications.

WARRANTY

T aæ Áwarrants that the products delivered pursuant to this specification (or order) will conform to the agreed specifications for twelve (12) months from the shipping date ("Warranty Period"). T aæ is obligated to repair or replace the products which are found to be defective or inconsistent with the specifications during the Warranty Period without charge, on condition that the products are stored or used as the conditions specified in the specifications. Nevertheless, T aæ is not obligated to repair or replace the products without charge if the defects or inconsistency are caused by the force majeure or the reckless behaviors of the customer.

After the Warranty Period, all repairs or replacements of the products are subject to charge.

MANUFACTURE • SUPPLY

FEATURES

Small molecular organic light emitting diode.

- Color: Yellow

- Panel resolution: 128*128

- Driver IC: SSD1327

- Excellent Quick response time: 10µs

- Extremely thin thickness for best mechanism design: 1.41 mm

- High contrast : 10000:1

- Wide viewing angle: Free

- Strong environmental resistance.
- 8-bit 6800-series Parallel Interface, 8-bit 8080-series Parallel Interface, Serial Peripheral Interface, I₂C Interface.
- Wide range of operating temperature : -40 to 80°C
- Anti-glare polarizer.

MECHANICAL DATA

NO	ITEM	SPECIFICATION	UNIT
1	Dot Matrix	128 x 128	dot
2	Dot Size	0.19 (W) x 0.19 (H)	mm ²
3	Dot Pitch	0.21 (W) x 0.21 (H)	mm ²
4	Aperture Rate	82	%
5	Active Area	26.86 (W) x 26.86 (H)	mm ²
6	Panel Size	33.8 (W) x 36.5 (H)	mm ²
7*	Panel Thickness	1.22 ± 0.1	mm
8	Module Size	33.8 (W) x 43.7 (H) x 1.41 (T)	mm ³
9	Diagonal A/A size	1.5	inch
10	Module Weight	3.48 ± 10%	gram

^{*} Panel thickness includes substrate glass, cover glass and UV glue thickness.



DESIGN • MANUFACTURE • SUPPLY

MAXIMUM RATINGS

ITEM	MIN	MAX	UNIT	Condition	Remark
Supply Voltage (Vcı)	-0.3	4	V	Ta = 25°C	IC maximum rating
Supply Voltage (Vcc)	8	19	V Ta = 25°C		IC maximum rating
Operating Temp.	-40	70	°C		
Storage Temp	-40	85	°C		
Humidity		85	%		
Life Time (30K)(typ)			Hrs	120 cd/m², 50% checkerboard	Note (1)
Life Time (40K)(typ)			Hrs	95 cd/m², 50% checkerboard	Note (2)
Life Time (50K)(typ)			Hrs	80 cd/m², 50% checkerboard	Note (3)

Note:

(A) Under Vcc = 15V, Ta = 25°C, 50% RH.

(B) Life time is defined the amount of time when the luminance has decayed to less than 50% of the initial measured luminance.

(1) Setting of 120 cd/m₂ :

Contrast setting : 0x74Frame rate : 105Hz

- Duty setting : 1/128

(2) Setting of 95 cd/m2 MANUFACTURE • SUPPLY

- Contrast setting : 0x60

Frame rate : 105HzDuty setting : 1/128

(3) Setting of 80 cd/m₂:

- Contrast setting : 0x4A

Frame rate : 105HzDuty setting : 1/128

ELECTRICAL CHARACTERISTICS

D.C ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETERS	TEST CONDITION	MIN	TYP	MAX	UNIT
Vcc	Driver power supply (for OLED panel)	-	14.5	15	15.5	V
Vcı	Low voltage power supply	-	2.6	1	3.5	V
Vон	High logic output level	lout=100 uA,	0.9* Vci	-	Vcı	V
Vol	Low logic output level	lout=100uA,	0	-	0.1* Vcı	V
VIH	High logic input level	lout=100uA,	0.8* Vci	-	Vcı	V
VIL	Low logic input level	lout=100uA,	0	-	0.2* Vcı	V
lcc	Vcc Supply Current	V _{Cl} = 3.5V, V _{Cc} = 18V, Display ON,	External V _{DD} = 2.5V	600	750	uA
		No panel attached, contrast = FF	Internal V _{DD} = 2.5V	600	750	
Icı	Vcı Supply Current	V _{Cl} = 3.5V, V _{Cc} = 18V, Display ON, No panel	External V _{DD} = 2.5V	35	50	uA
		attached, contrast = FF	Internal V _{DD} = 2.5V	95	120	
		Contrast=FF	-	300	370	uA
_	Segment output	Contrast=AF	-	206	-	uA
ISEG	current Setting	Contrast=7F	-	150	_	uA
	Vcc=18V, IREF=10uA	Contrast=3F	-	75	-	uA
		Contrast=1F	-	37.5	-	uA

ELECTRO-OPTICAL CHARACTERISTICS

PANEL ELECTRICAL SPECIFICATIONS

PARAMETER	MIN	TYP.	MAX	UNITS	COMMENTS
Normal mode current consumption	-	15	17	mA	All pixels on
Standby mode current consumption	-	1	2	mA	Standby mode 10% pixels on
Normal mode power consumption	-	225	255	mW	All pixels on
Standby mode power consumption	-	15	30	mW	Standby mode 10% pixels on
Pixel Luminance	80	100		cd/m ²	Display Average
Standby Luminance		25		cd/m ²	
CIEx (Yellow)	0.43	0.47	0.51		CIE1931
CIEy (Yellow)	0.48	0.52	0.56		CIE1931
Dark Room Contrast	10000:1				
Viewing Angle		Free		degree	
Response Time		10		μs	

Normal mode condition :

- Driving Voltage: 15V

- Contrast setting : 0x60

- Frame rate : 105Hz- Duty setting : 1/128

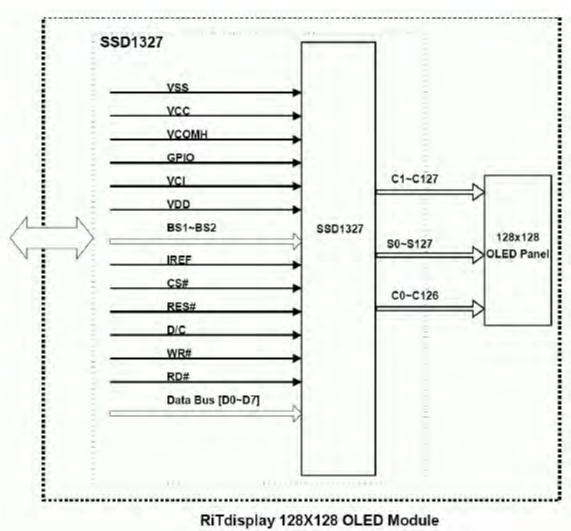
Standby mode condition :

D-E Driving Voltage: 15VANUFACTURE • SUPPLY

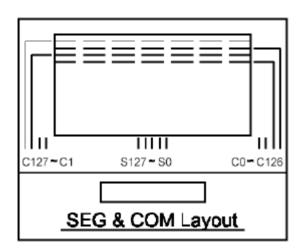
Contrast setting: 0x00Frame rate: 105HzDuty setting: 1/128

INTERFACE

FUNCTION BLOCK DIAGRAM



PANEL LAYOUT DIAGRAM



PIN ASSIGNMENTS

PIN NAME	PIN NO	DESCRIPTION
VSS	1	Ground.
VCC	2	Power supply for analog circuit.
VCOMH	3	Com Voltage Output. A capacitor should be connected between this pin and Vss.
GPIO	4	General I/O port.
VCI	5	Power supply for logic circuit.
VDD	6	A capacitor should be connected between this pin and Vss.
BS1	7	MCU bus interface selection pins.
BS2	8	MCU bus interface selection pins.
VSS	9	Ground.
IREF	10	Reference current input pin. A resistor should be connected between this pin and Vss.
CS#	11	Chip select input.
RES#	12	Reset signal input. When it's low, initialization of SSD1327 is executed.
D/C	13	Data/ Command control. Pull high for write/read display data. Pull low for write command or read status.
WR#	14	MCU interface input. Data write operation is initiated when it's pull low.
RD#	15	MCU interface input. Data read operation is initiated when it's pull low.
D0	16	
D1	17	
D2	18	
D3	19	Data bus(for parallel interface)
D4	20	
D5	21	
D6	22	
D7	23	
VCC	24	Power supply for analog circuit.
VSS	25	Ground.

GRAPHIC DISPLAY DATA RAM ADDRESS MAP

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 128x128x4 bits. For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software. The GDDRAM address maps below tables show some examples on using the command "Set Re-map" A0h to re-map the GDDRAM. In the following tables, the lower nibble and higher nibble of D0, D1, D2 ... D8189, D8190, D8191 represent the 128x128 data bytes in the GDDRAM.

The GDDRAM map under the following condition:

Command "Set Re-map" A0h is set to:

Disable Column Address Re-map (A[0]=0)

Disable Nibble Re-map (A[1]=0)

Enable Horizontal Address Increment (A[2]=0)

Disable COM Re-map (A[4]=0)

Display Start Line=00h

Data byte sequence: D0, D1, D2 ... D8191

GDDRAM address map 1 SEG 127 SEC Outputs Column Address D0[7.4] D11901 D117.41 CONG 130Ff-01 1062(3:0) D6349 01 D63(7:4) (IKEN) D126[3:0] D1267:4 D64[3:0] D64[7:4] 065[3:0] D65(7.4) D127[3:0] D127/7 COM 03 0201/120 7E COMME 71 COM Address Outputs (HEX) Nibble re-map A[1]=0

The GDDRAM map under the following condition:

Command "Set Re-map" A0h is set to:

Disable Column Address Re-map (A[0]=0)

Disable Nibble Re-map (A[1]=0)

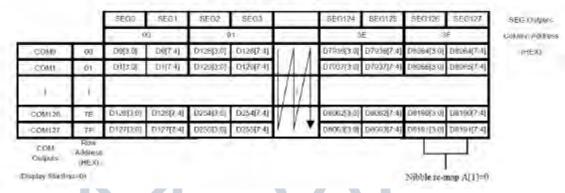
Enable Vertical Address Increment (A[2]=1)

Disable COM Re-map (A[4]=0)

Display Start Line=00h

Data byte sequence: D0, D1, D2 ... D8191

GDDRAM address map 2



The GDDRAM map under the following condition:

Command "Set Re-map" A0h is set to:

Enable Column Address Re-map (A[0]=1)

Enable Nibble Re-map (A[1]=1)

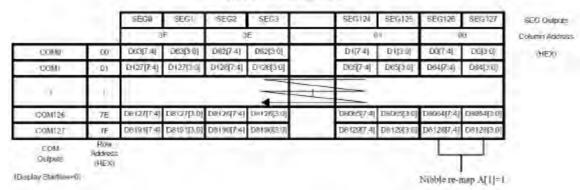
Enable Horizontal Address Increment (A[2]=0)

Disable COM Re-map (A[4]=0)

Display Start Line=00h

Data byte sequence: D0, D1, D2 ... D8191

GDDRAM address map 3



The example in which the display start line register is set to 10h with the following condition:

Command "Set Re-map" A0h is set to:

Disable Column Address Re-map (A[0]=0)

Disable Nibble Re-map (A[1]=0)

Enable Horizontal Address Increment (A[2]=0)

Enable COM Re-map (A[4]=1)

Display Start Line=78h (corresponds to COM119)

Data byte sequence: D0, D1, D2 ... D8191

GDDRAM address map 4

		SEGO.	SEGT	SEG2	SEG3		5EG124	SEG125	SEG126	BEG127	SEG Culpu
	- 1	0	o .		100		- 2	E	. 3	F	Column Addi
COMITIS	00	Dulard	0054	[04][10]	D4[7:4]		D65(3.0)	1832[7-4]	D63[30]	D83[7-4]	(HEK)
COM18	0.1	Diffici	[364]7.4]	D65[3:0]	D65[7-4]	9	0.26(9.0)	D1287-4]	D127[3.0]	Dt27[7:4]	
140	Ł										
COM121	7E	0126(3.0)	D9064[7.4]	Defect(3:0)	DB082[7:4]	7	De12((3:0)	D8126[7:4]	De/127[3:0]	[09127]7:4)	
C/3M120	JF.	0127[3:0]	D8128[7:a]	D8 (29(3.0)	D8129[7.4]		D8190[3:0]	D8190[7,4]	De191[3.0]	D8 19 [7 4]	
Outputs Outputs	Prow Printers (HEX)									- 1	
splay Startine:78n									XTICL 1	nssp A[1]=0	

The GDDRAM map under the following condition:

Command "Set Re-map" A0h is set to:

Disable Column Address Re-map (A[0]=0)

Disable Nibble Re-map (A[1]=0)

Enable Horizontal Address Increment (A[2]=0)

Disable COM Re-map (A[4]=0)

Display Start Line=00h

Column Start Address=01h UFACTURE • SUPPLY

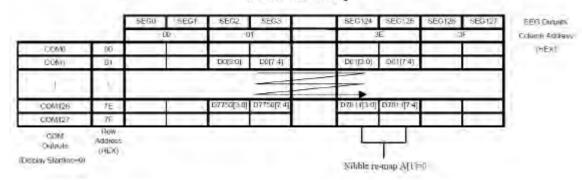
Column End Address=3Eh

Row Start Address=01h

Row End Address=7Eh

Data byte sequence: D0, D1, D2 ... D7811

GDDRAM address map 5



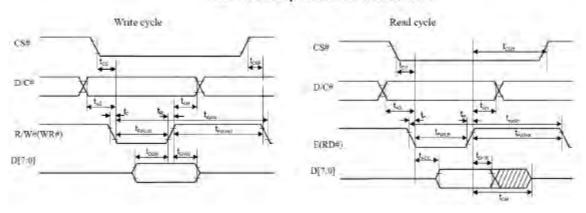
INTERFACE TIMING CHART

8080-Series MCU Parallel Interface Timing Characteristics

$(V_{DD} - V_{SS} = 2.4 \text{ to } 2.6 \text{V}, V_{CI} = 3.3 \text{V}, T_A$

Symbol	Parameter	Min	Typ	Max	Unit
texte	Clock Cycle Time	300	-3	-2	115
t _{A5}	Address Setup Time	10	- 1	10.00	TIS
t _{AH}	Address Hold Time	0			115
t _{DSW}	Write Data Setup Time	40		-2-	iis
tonw	Write Data Hold Time	7	-	-71	IIS
tona	Read Data Hold Time	20		54.5	ns
t _{on}	Output Disable Time		E - 60 T	70	118
tatt	Access Time			140	118
t _{PWLR}	Read Low Time	150	1-80	1	118
tpwiw	Write Low Time	60			IIS
t _{PWHB}	Read High Time	60	-		ns
tewnw	Write High Time	-60	1 -	10.2	115
T ₀	Rise Time		Ψ.	15	118
t _F	Fall Time		1	1.5	TIS.
tcs	Chip select setup time	0.	70-0	100	315
CSH	Chip select hold time to read signal	0	-		ns
CSF	Chip select hold time	20			Tis-

8080-series MCU parallel interface characteristics

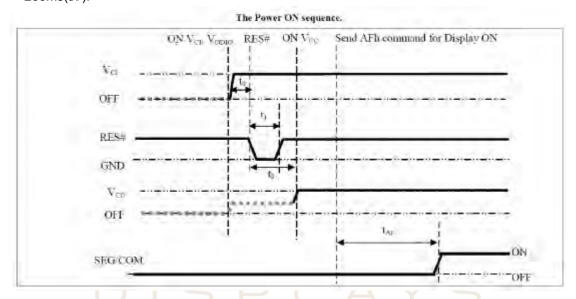


POWER ON / OFF SEQUENCE & APPLICATION CIRCUIT

POWER ON / OFF SEQUENCE

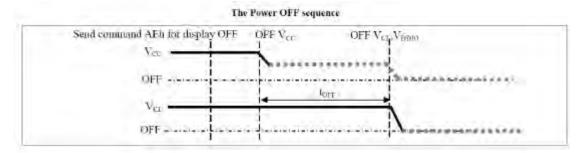
Power ON sequence:

- 1. Power ON Vci.
- 2. After V_{CI} becomes stable, set wait time at least 1ms (t₀) for internal V_{DD} become stable. Then set RES# pin LOW (logic low) for at least 100us (t₁) (4) and then HIGH (logic high).
- 3. After set RES# pin LOW (logic low), wait for at least 100us (t2). Then Power ON Vcc.(1)
- 4. After Vcc become stable, send command AFh for display ON. SEG/COM will be ON after 200ms(taf).



Power OFF sequence:

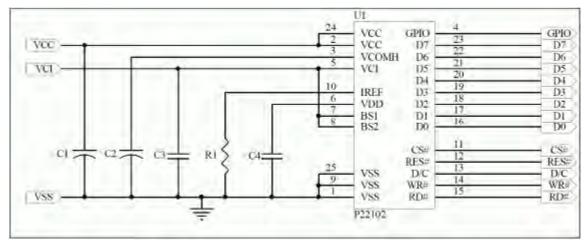
- 1. Send command AEh for display OFF.
- 2. Power OFF Vcc.(1), (2), (3)
- 3. Wait for toff. Power OFF Vol. (where Minimum toff=80ms (5), Typical toff=100ms)



Note:

- (1) Since an ESD protection circuit is connected between V_{Cl} and V_{CC} , V_{CC} becomes lower than V_{Cl} whenever V_{Cl} is ON and V_{CC} is OFF as shown in the dotted line of V_{CC} in above figures.
- (2) Vcc should be kept disable when it is OFF.
- (3) Power pins (Vci, Vcc) can never be pulled to ground under any circumstance.
- (4) The register values are reset after t₁.
- (5) Vci should not be Power OFF before Vcc Power OFF

APPLICATION CIRCUIT



Component:

C1, C2: 4.7uF/35V(Tantalum type) or VISHAY (572D475X0025A2T)

C3, C4: 1uF/16V(0603)

R1: 1M ohm (0603) 1%

This circuit is for 8080 8bits interface.

COMMAND TABLE Refer

to IC Spec.: SSD1327
DESIGN • MANUFACTURE • SUPPLY

RELIABILITY TEST CONDITIONS

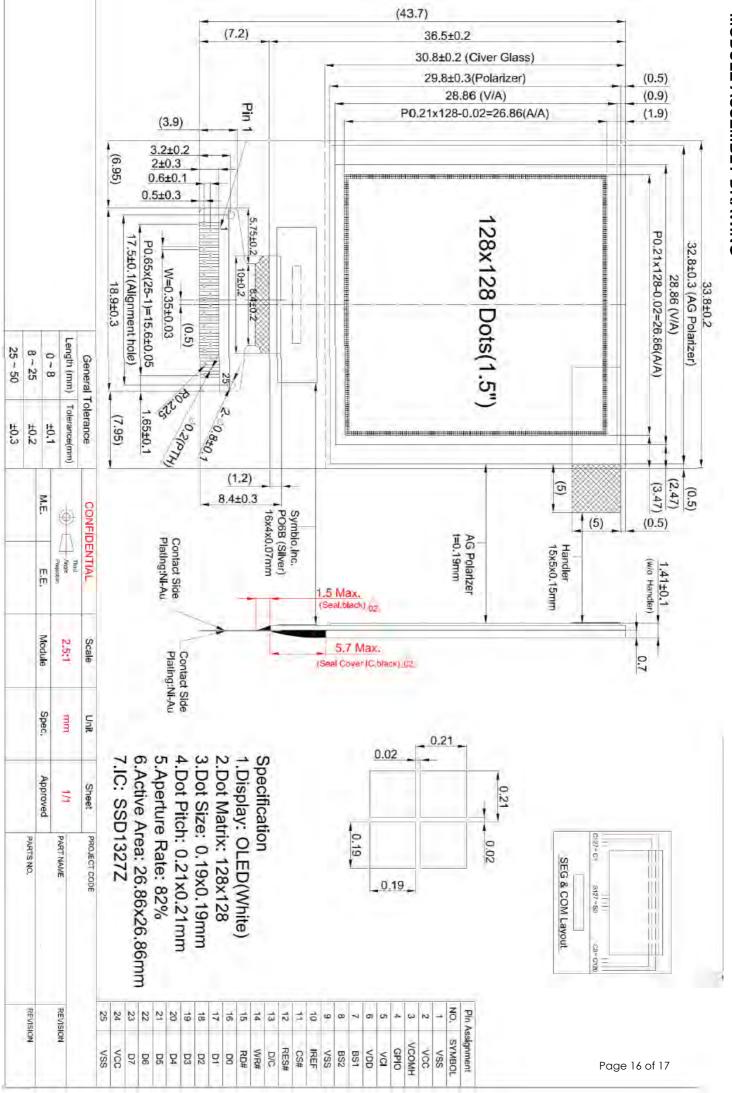
No.	Items	Specification	Quantity
1	High temp. (Non-operation)	85°C, 240hrs	5
2	High temp. (Operation)	70°C, 120hrs	5
3	Low temp. (Operation)	-40°C, 120hrs	5
4	High temp. / High humidity (Operation)	65°C, 90%RH, 120hrs	5
5	Thermal shock (Non-operation)	-40°C ~85°C (-40°C /30min; transit /3min; 85°C /30min; transit /3min) 1cycle: 66min, 100 cycles	5
6	Vibration	Frequency: 5~50HZ, 0.5G Scan rate: 1 oct/min Time: 2 hrs/axis Test axis: X, Y, Z	1 Carton
7	Drop	Height: 120cm Sequence: 1 angle \ 3 edges and 6 faces Cycles: 1	1 Carton
8	ESD (Non-operation)	Air discharge model, ±8kV, 10 times	5

Test and measurement conditions ACTURE • SUPPLY

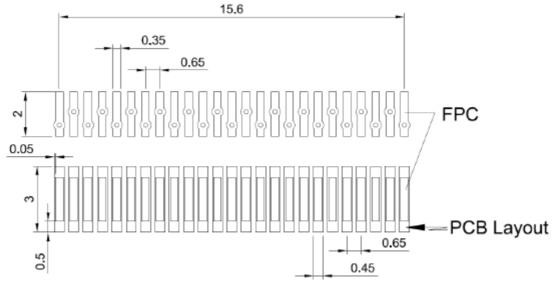
- 1. All measurements shall not be started until the specimens attain to temperature stability.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for item 1, 4 & 5.

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.



FOOTPRINT DRAWING





DESIGN • MANUFACTURE • SUPPLY